(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property **Organization**

International Bureau



(43) International Publication Date 10 March 2005 (10.03.2005)

PCT

(10) International Publication Number WO 2005/022607 A1

(51) International Patent Classification⁷:

H01L 21/00

(21) International Application Number:

PCT/JP2004/012600

(22) International Filing Date: 25 August 2004 (25.08.2004)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

2003-302782

27 August 2003 (27.08.2003)

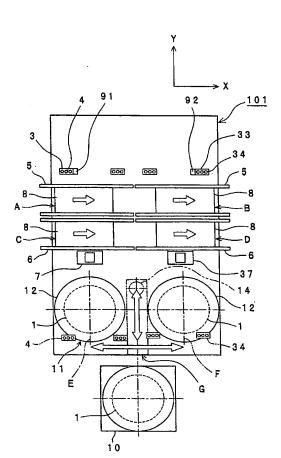
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- (81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN. CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.
- (84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM. ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM),

[Continued on next page]

(54) Title: COMPONENT MOUNTING APPARATUS AND COMPONENT MOUNTING METHOD



(57) Abstract: A component mounting apparatus (101) is provided with a board holding device (5, 6) for holding a board (8) at a board holding position (A, B, C and D), a first mounting head (4) for holding and taking out a component (2) fed from a first component feeding position (E) and mounting the component on the board held at the board holding position, a second mounting head (34) for holding and taking out the component fed from a second component feeding position (F) and mounting the component on the held board, and a component feeding device (11) having a wafer holding table (12) for holding a wafer (1) on which the respective components are fed so that the wafer holding table can be moved reciprocationally between the first component feeding position and the second component feeding position.

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European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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